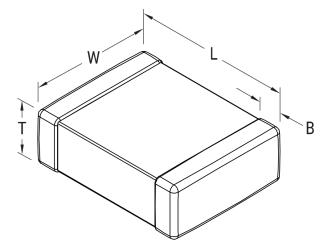


CKC33C473GCGAC7210

KC-LINK Comm COG, Ceramic, 0.047 uF, 2%, 500 VDC, COG, SMD, MLCC, Ultra-Stable, Low Loss, Class I, 3640



Click here for the 3D model.

| Dimensions | |
|------------|-----------------|
| Chip Size | 3640 |
| L | 9.3mm +/-0.6mm |
| W | 10.2mm +/-0.4mm |
| Т | 2.5mm +/-0.20mm |
| В | 1.27mm +/-0.4mm |

| Packaging Specifications | |
|--------------------------|--|
| astic Tape | |
| | |
| | |

| General Information | |
|---------------------|--|
| Series | KC-LINK Comm COG |
| Style | SMD Chip |
| Description | SMD, MLCC, Ultra-Stable, Low Loss, Class I |
| Features | Ultra-Stable, Low Loss, Class I |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 1.06 g |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | | |
|--|---------------------------|--|
| Capacitance | 0.047 uF | |
| Measurement Condition | 1 kHz 1.0Vrms | |
| Capacitance Tolerance | 2% | |
| Voltage DC | 500 VDC | |
| Dielectric Withstanding Voltage | 750 VDC | |
| Temperature Range | -55/+150°C | |
| Temperature Coefficient | COG | |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms | |
| Dissipation Factor | 0.1% 1 kHz 1.0Vrms | |
| Aging Rate | 0% Loss/Decade Hour | |
| Insulation Resistance | 21.2766 GOhms | |

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